

**Microsemi Corporation**

January 09, 2017

**Product/Process Change Notification No: 0317****Change Classification: Major; Packing Method****Subject: Label and Packing Material Changes****Description of Change:**

Microsemi Ethernet and Networking Technologies (ENT) is changing the packing materials and all packing labels for our products. The changes are detailed in the provided attachment.

**Reason for Change:**

Microsemi ENT is standardizing the packing material and labeling.

**Products Affected by this Change:**

All Microsemi ENT products are affected. ENT product numbers begin with "VSC."

**Production Shipment Schedule:**

Effective February 9, 2017, shipments may have the new labels and packing materials.

**Contact Information:**

If you have further questions related to this topic, contact Microsemi's Technical Support at [ENT.quality@microsemi.com](mailto:ENT.quality@microsemi.com).

Regards,

Microsemi Corporation

Any projected dates in this PCN are based on the most current product information at the time this PCN is being issued, but they may change due to unforeseen circumstances. For the latest schedule and any other information, please contact your local Microsemi Sales Office, the factory contact shown above, or your local distributor.

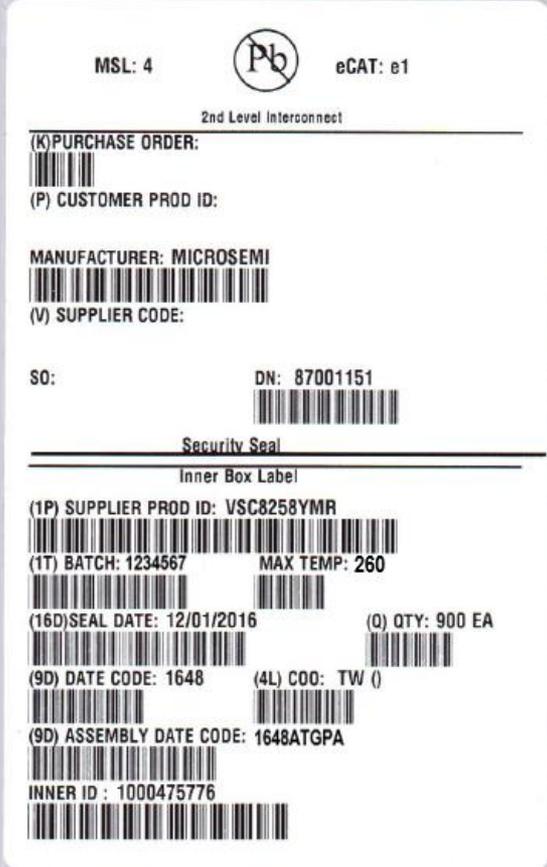
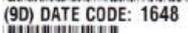
This Product/Process Change Notification is confidential and proprietary information of Microsemi and is intended only for distribution by Microsemi to its customers, for customers' use only. It must not be copied or provided to any third party without Microsemi's prior written consent.



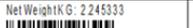
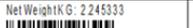
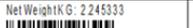
# PCN0317

## Label & Packing Information

# Label Information

Item	From	To														
Inner Label	<table border="1"> <tr> <td>(1P) Supplier Product ID: VSC8258YMR </td> <td>(V) Vendor Name: Microsemi </td> </tr> <tr> <td>(P) Item ID Code: 012100100222 </td> <td>Mfg Part No: 602474AAA </td> </tr> <tr> <td>(9D) Assembly Date Code: 1648ATGPA </td> <td>(11D) Date Code: 1648 </td> </tr> <tr> <td>(1T) Lot Number: FT1549900.4.G.99.S2 </td> <td>(Q) Quantity: 336 </td> </tr> <tr> <td>(4L) Country of Origin: TAIWAN </td> <td>2nd level interconnect Pb - free (e1) Max Safe Temp 260C </td> </tr> <tr> <td>(14K) Trans ID: KWA1601_001_021P </td> <td>MSL: 4 </td> </tr> <tr> <td colspan="2">(1T) Lot#-Qty: FT1549900.4.G.99.S2-336 </td> </tr> </table>	(1P) Supplier Product ID: VSC8258YMR 	(V) Vendor Name: Microsemi 	(P) Item ID Code: 012100100222 	Mfg Part No: 602474AAA 	(9D) Assembly Date Code: 1648ATGPA 	(11D) Date Code: 1648 	(1T) Lot Number: FT1549900.4.G.99.S2 	(Q) Quantity: 336 	(4L) Country of Origin: TAIWAN 	2nd level interconnect Pb - free (e1) Max Safe Temp 260C 	(14K) Trans ID: KWA1601_001_021P 	MSL: 4 	(1T) Lot#-Qty: FT1549900.4.G.99.S2-336 		 <p>MSL: 4  eCAT: e1</p> <p>2nd Level Interconnect</p> <p>(K) PURCHASE ORDER: </p> <p>(P) CUSTOMER PROD ID: </p> <p>MANUFACTURER: MICROSEMI </p> <p>(V) SUPPLIER CODE: </p> <p>S0:  DN: 87001151 </p> <p>Security Seal</p> <p>Inner Box Label</p> <p>(1P) SUPPLIER PROD ID: VSC8258YMR </p> <p>(1T) BATCH: 1234567  MAX TEMP: 260 </p> <p>(16D) SEAL DATE: 12/01/2016  (Q) QTY: 900 EA </p> <p>(9D) DATE CODE: 1648  (4L) COO: TW () </p> <p>(9D) ASSEMBLY DATE CODE: 1648ATGPA </p> <p>INNER ID : 1000475776 </p>
(1P) Supplier Product ID: VSC8258YMR 	(V) Vendor Name: Microsemi 															
(P) Item ID Code: 012100100222 	Mfg Part No: 602474AAA 															
(9D) Assembly Date Code: 1648ATGPA 	(11D) Date Code: 1648 															
(1T) Lot Number: FT1549900.4.G.99.S2 	(Q) Quantity: 336 															
(4L) Country of Origin: TAIWAN 	2nd level interconnect Pb - free (e1) Max Safe Temp 260C 															
(14K) Trans ID: KWA1601_001_021P 	MSL: 4 															
(1T) Lot#-Qty: FT1549900.4.G.99.S2-336 																

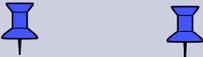
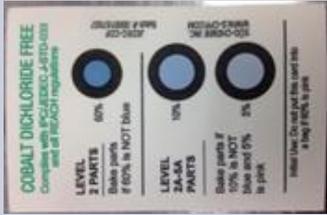
# Label Information

Item	From	To																														
Outer Shipping Label	<p><b>Ship From:</b> Address here</p> <p><b>Ship To:</b> Customer Name Customer Address</p> <hr/> <p><b>SO: 110442</b></p> <table border="1"> <tr> <td>(1P) Supplier Prod ID: VSC8258YMR </td> <td>(V) Vendor Name: Microsemi </td> </tr> <tr> <td>(P) Customer Product ID: </td> <td>Mfg Part No: 602890BBA </td> </tr> <tr> <td>(14K) Trans ID: VSTDOH14082701 </td> <td>Number of Pkg/Cms: 1 of 1 </td> </tr> <tr> <td>Box Dimensions: 435 X 370 X 165 (mm) </td> <td>(Q) Quantity in Box: 240 of 240 </td> </tr> <tr> <td>Gross Weight KG: 3.508333 </td> <td>Net Weight KG: 2.245333 </td> </tr> <tr> <td colspan="2">(4L) Country of Origin: TAIWAN </td> </tr> </table>	(1P) Supplier Prod ID: VSC8258YMR 	(V) Vendor Name: Microsemi 	(P) Customer Product ID: 	Mfg Part No: 602890BBA 	(14K) Trans ID: VSTDOH14082701 	Number of Pkg/Cms: 1 of 1 	Box Dimensions: 435 X 370 X 165 (mm) 	(Q) Quantity in Box: 240 of 240 	Gross Weight KG: 3.508333 	Net Weight KG: 2.245333 	(4L) Country of Origin: TAIWAN 		<p><b>CUSTOMER NAME</b> Customer Address</p> <hr/> <p>(3S) PKG ID: 062169587001151 </p> <p>(14K) Trans ID: 4500043100 </p> <p>MANUFACTURER: MICROSEMI </p> <p>(V) SUPPLIER CODE: </p> <p>DN: 87001151 </p> <p>(P) CUSTOMER PROD ID: </p> <p>(Q) TOTAL BOX QTY: 2000 </p> <table border="1"> <tr> <td>PACKAGE COUNT: 1 OF 1</td> <td>PACKAGE WEIGHT: 6 KG</td> </tr> </table> <p>OUTER ID: 297607 </p> <hr/> <p>Outer ID : 297607 </p> <p>Box Content Label</p> <hr/> <p>Customer: <b>CUSTOMER NAME</b></p> <p>Box Details: Gross Weight: 5.5 Kg Net Weight: 5.2 Kg Measures: 38.6 X 37.2 X 18.8 cm (L x W x H)</p> <table border="1"> <thead> <tr> <th>Order</th> <th>Part No / Inner ID</th> <th>Qty</th> </tr> </thead> <tbody> <tr> <td>10-4500043100</td> <td>VSC8258YMR-</td> <td></td> </tr> <tr> <td></td> <td>1000475776</td> <td>900</td> </tr> <tr> <td></td> <td>1000475777</td> <td>900</td> </tr> <tr> <td></td> <td>1000475778</td> <td>200</td> </tr> </tbody> </table>		PACKAGE COUNT: 1 OF 1	PACKAGE WEIGHT: 6 KG	Order	Part No / Inner ID	Qty	10-4500043100	VSC8258YMR-			1000475776	900		1000475777	900		1000475778	200
(1P) Supplier Prod ID: VSC8258YMR 	(V) Vendor Name: Microsemi 																															
(P) Customer Product ID: 	Mfg Part No: 602890BBA 																															
(14K) Trans ID: VSTDOH14082701 	Number of Pkg/Cms: 1 of 1 																															
Box Dimensions: 435 X 370 X 165 (mm) 	(Q) Quantity in Box: 240 of 240 																															
Gross Weight KG: 3.508333 	Net Weight KG: 2.245333 																															
(4L) Country of Origin: TAIWAN 																																
PACKAGE COUNT: 1 OF 1	PACKAGE WEIGHT: 6 KG																															
Order	Part No / Inner ID	Qty																														
10-4500043100	VSC8258YMR-																															
	1000475776	900																														
	1000475777	900																														
	1000475778	200																														

# Label Information

Item	From	To
MSL Label	<div data-bbox="336 665 971 1022" data-label="Complex-Block">  <p style="text-align: center;"><b>Caution</b> This bag contains <b>MOISTURE- SENSITIVE DEVICES</b></p> <div style="float: right; border: 1px solid black; padding: 2px; text-align: center; width: 20px;">4</div> <p style="text-align: right; margin-right: 20px;">Level</p> <ol style="list-style-type: none"> <li>1) Shelf life in sealed bag: 24months at &lt; 40 deg.C and &lt; 90% Relative Humidity (RH).</li> <li>2) Peak package body temperature as defined by IPC/JEDEC J- STD- 020.</li> <li>3) After bag is opened, devices that will be subjected to reflow solder or other high temperature process must be:             <ol style="list-style-type: none"> <li>a) Mounted within 72 hours at factory conditions &lt; = 30deg. C/60% RH or</li> <li>b) Stored per J- STD- 033.</li> </ol> </li> <li>4) Devices require baking before mounting, if             <ol style="list-style-type: none"> <li>a) Humidity indicator card reads &gt; 10% for level 2a - 5a devices or &gt; 60% for level 2 devices when read at 23 +/- 5 deg.C.</li> <li>b) 3a or 3b are not met.</li> </ol> </li> <li>5) If baking is required, refer to IPC/JEDEC J- STD- 033 for bake procedure.</li> </ol> <p>Bag Seal Date: <u>04 /09 / 2013</u></p> <p>Note: Level and body temperature defined by IPC/JEDEC J- STD- 020</p> </div>	<div data-bbox="1136 605 1678 1186" data-label="Complex-Block">  <p style="text-align: right;"><b>Moisture Sensitivity Level</b></p> <div style="float: right; border: 1px solid black; width: 40px; height: 20px; margin-right: 10px;"></div> <p style="text-align: right; font-size: small;">If blank, see adjacent printed label</p> <p style="text-align: center;"><b>WARNING - THESE DEVICES ARE MOISTURE SENSITIVE</b></p> <p>Shelf life in sealed bag is 24 months at &lt;40C and &lt;90% Relative Humidity (RH).</p> <p>After bag is opened, devices that will be subjected to reflow solder or other high temperature processes must be:</p> <ol style="list-style-type: none"> <li>a) stored per J-STD-033 or</li> <li>b) be mounted under the following conditions:</li> </ol> <p>If MSL 1 no special conditions if stored at factory conditions &lt;30C / &lt;85%RH</p> <p>If MSL 2 mount devices within 1 year at factory conditions &lt;30C / &lt;60%RH</p> <p>If MSL 3 mount devices within 168 hours at factory conditions &lt;30C / 60%RH</p> <p>If MSL 4 mount devices within 72 hours at factory conditions &lt;30C / 60%RH</p> <p>If MSL 5 mount devices within 48 hours at factory conditions &lt;30C / 60%RH</p> <p>If MSL 5a mount devices within 24 hours at factory conditions &lt;30C / 60%RH</p> <p>If units are not to be used within the recommended timeframe, reseal or store &lt;10%RH</p> <p>Devices require bake prior to mount if:</p> <ul style="list-style-type: none"> <li>- humidity indicator card reads &gt;10% for level 2a-5a devices or &gt;60% for level 2 devices when read at 23C (+/-5C) or</li> <li>- a) and b) are not met.</li> </ul> <p>Refer to IPC/JEDEC J-STD-033 for bake procedure Recommended reflow conditions, level and peak package body temperature are defined by IPC/JEDEC J-STD-020.</p> </div>

# Packing Information

Item	From	To
Bubble Wrap	20"x19" 	24"x24" 
Moisture Barrier Bag	10"x20" 	10"x22" 
Humidity Indicator Card	Sud-Chemie: 200014484 	Dessicare Inc 04BW14C10 

# Packing Information

Item	From	To
Desiccant	Sud-Chemie Desi Pak Tyvek 	Dessicare Inc 02BM10A16 
Inner Boxes	14.76"x5.98"x3.39" (LxWxH) 	14.5"x7"x3.25" (LxWxH) 



**Microsemi Corporate Headquarters**  
One Enterprise, Aliso Viejo, CA 92656 USA  
Within the USA: +1 (800) 713-4113  
Outside the USA: +1 (949) 380-6100  
Sales: +1 (949) 380-6136  
Fax: +1 (949) 215-4996  
email: [sales.support@microsemi.com](mailto:sales.support@microsemi.com)  
[www.microsemi.com](http://www.microsemi.com)

Microsemi Corporation (MSCC) offers a comprehensive portfolio of semiconductor and system solutions for communications, defense & security, aerospace and industrial markets. Products include high-performance and radiation-hardened analog mixed-signal integrated circuits, FPGAs, SoCs and ASICs; power management products; timing and synchronization devices and precise time solutions, setting the world's standard for time; voice processing devices; RF solutions; discrete components; enterprise storage and communication solutions, security technologies and scalable anti-tamper products; Ethernet solutions; Power-over-Ethernet ICs and midspans; as well as custom design capabilities and services. Microsemi is headquartered in Aliso Viejo, Calif., and has approximately 4,800 employees globally. Learn more at [www.microsemi.com](http://www.microsemi.com)

Microsemi makes no warranty, representation, or guarantee regarding the information contained herein or the suitability of its products and services for any particular purpose, nor does Microsemi assume any liability whatsoever arising out of the application or use of any product or circuit. The products sold hereunder and any other products sold by Microsemi have been subject to limited testing and should not be used in conjunction with mission-critical equipment or applications. Any performance specifications are believed to be reliable but are not verified, and Buyer must conduct and complete all performance and other testing of the products, alone and together with, or installed in, any end-products. Buyer shall not rely on any data and performance specifications or parameters provided by Microsemi. It is the Buyer's responsibility to independently determine suitability of any products and to test and verify the same. The information provided by Microsemi hereunder is provided "as is, where is" and with all faults, and the entire risk associated with such information is entirely with the Buyer. Microsemi does not grant, explicitly or implicitly, to any party any patent rights, licenses, or any other IP rights, whether with regard to such information itself or anything described by such information. Information provided in this document is proprietary to Microsemi, and Microsemi reserves the right to make any changes to the information in this document or to any products and services at any time without notice.

©2016 Microsemi Corporation. All rights reserved. Microsemi and the Microsemi logo are registered trademarks of Microsemi Corporation. All other trademarks and service marks are the property of their respective owners.